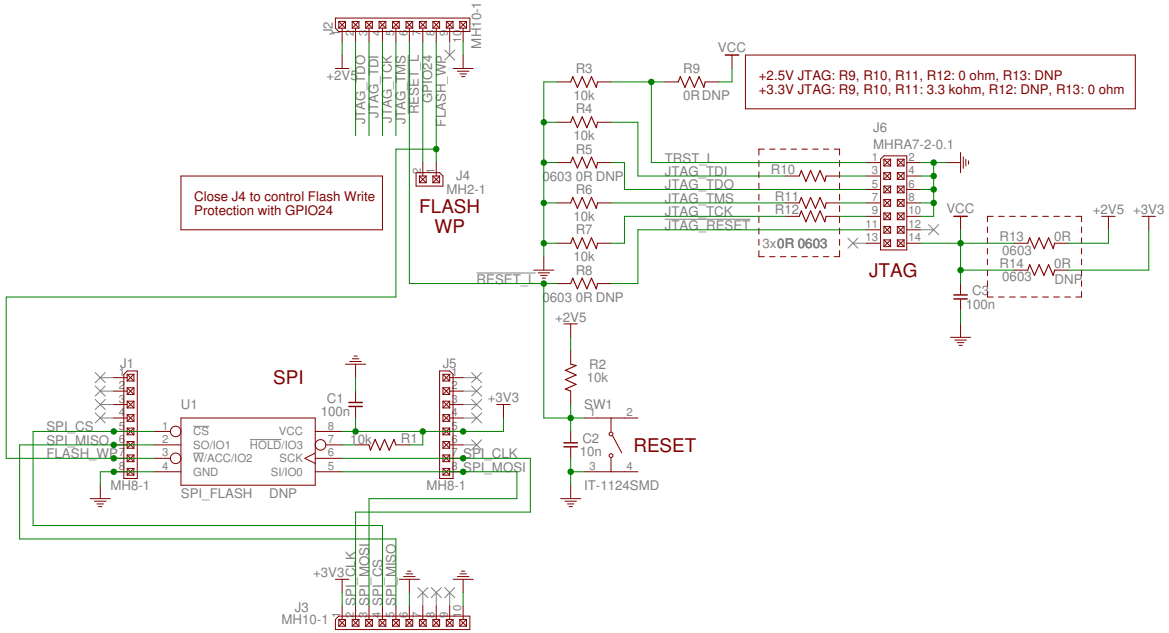

Resistors are 5% 1/16W 0402 unless otherwise specified
Ceramic capacitors are ±10% 50V X7R dielectric 0402 unless otherwise specified

Domino Core
Domino Pi
Domino Qi

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Domino JTAG SPI

24/08/14 11:49

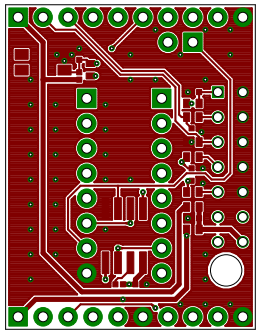
Sheet: 1/1

Rev.A

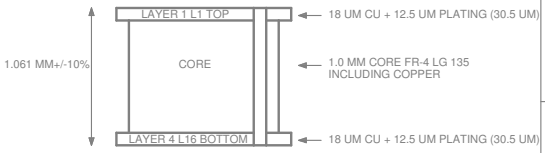
LAYER-STACK

DRILL CHART: TOP TO BOTTOM

Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	61	YES
×	2	36	0.91	14	YES
◳	3	40	1.02	38	YES
◇	4	126	3.20	1	NOT



STACK-UP FOR REFERENCE



NOTES:

1. PRINTED CIRCUIT BOARD MADE FROM NEMA GRADE FR-4 TG 135 EPOXY LAMINATE WITH 18 UM COPPER PLATING AND 1 MM THICKNESS.
2. ALL DIMENSIONS ARE GIVEN IN MILLIMETERS EXCEPT TRACE WIDTH/SPACE.
3. CIRCUIT PATHS ARE FOR REFERENCE ONLY.
4. HOLE SIZES SHOWN ARE FINISHED DIAMETERS AFTER PLATING.
5. BOARD PLATED USING REFLOW OR SIMILAR METHOD.
6. BOARD TO HAVE WHITE SOLDER MASK ON PLATED SURFACES USING WET FILM SR100 OR SR1010 EPOXY.
EQUIVALENT WET OR DRY FILM MAY BE USED.
7. SILKSCREEN BOARD USING BLACK INK. DISTORTION OF SILKSCREEN IS ACCEPTABLE OVER TRACES. EPOXY INK ON PLATED LANDS IS NOT ACCEPTABLE
8. THE FOLLOWING INFORMATION APPLIES TO THIS BOARD:
   * 2 COPPER LAYERS
   * 1 MM BOARD THICKNESS
   * REQUIRES TOP AND BOTTOM SIDE SILKSCREENS

Domino Core

Domino Pi

Domino Qi

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Domino JTAG SPI

24/08/14 11:50

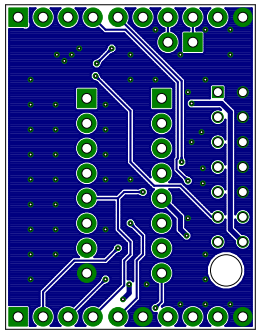
Component Side (.CMP)

Rev. B

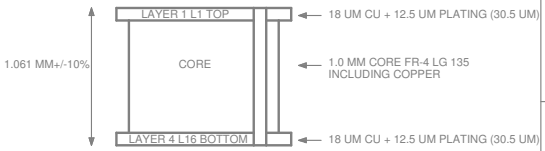
LAYER-STACK

DRILL CHART: TOP TO BOTTOM

Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	61	YES
×	2	36	0.91	14	YES
◳	3	40	1.02	38	YES
◇	4	126	3.20	1	NOT



STACK-UP FOR REFERENCE



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   * 1 MM BOARD THICKNESS
   * REQUIRES TOP AND BOTTOM SIDE SILKSCREENS

Domino Core

Domino Pi

Domino Qi

Domino JTAG SPI

24/08/14 11:50

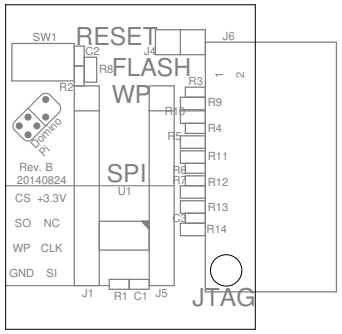
Solder side (.SOL)

Rev. B

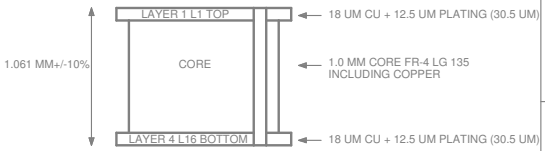
DRILL CHART: TOP TO BOTTOM

Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	61	YES
×	2	36	0.91	14	YES
◳	3	40	1.02	38	YES
◇	4	126	3.20	1	NOT

LAYER-STACK



STACK-UP FOR REFERENCE



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   * 1 MM BOARD THICKNESS
   * REQUIRES TOP AND BOTTOM SIDE SILKSCREENS

Domino Core Domino Pi Domino Qi

Domino JTAG SPI

24/08/14 11:50

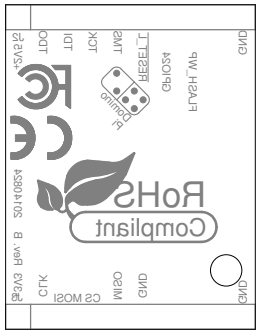
Silk screen CMP (.PLC)

Rev. B

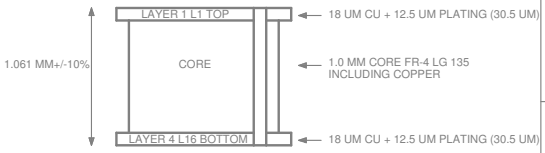
DRILL CHART: TOP TO BOTTOM

Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	61	YES
×	2	36	0.91	14	YES
◳	3	40	1.02	38	YES
◈	4	126	3.20	1	NOT

LAYER-STACK



STACK-UP FOR REFERENCE



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Domino Core

Domino Pi

Domino Qi

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Domino JTAG SPI

24/08/14 11:50

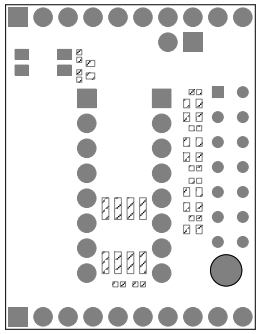
Silk screen SOL (.PLS)

Rev. B

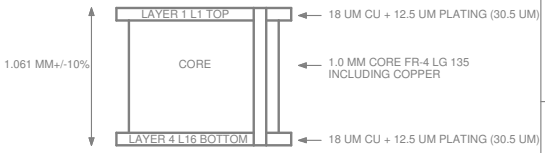
LAYER-STACK

DRILL CHART: TOP TO BOTTOM

Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	61	YES
×	2	36	0.91	14	YES
◳	3	40	1.02	38	YES
◇	4	126	3.20	1	NOT



STACK-UP FOR REFERENCE



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Domino Core

Domino Pi

Domino Qi

Domino JTAG SPI

24/08/14 11:50

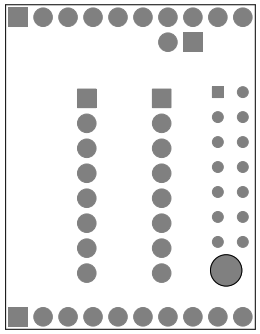
Solder stop mask CMP (.STC)

Rev. B

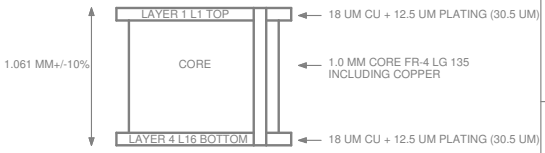
DRILL CHART: TOP TO BOTTOM

Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	61	YES
×	2	36	0.91	14	YES
◳	3	40	1.02	38	YES
◇	4	126	3.20	1	NOT

LAYER-STACK



STACK-UP FOR REFERENCE



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Domino Core

Domino Pi

Domino Qi

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Domino JTAG SPI

24/08/14 11:50

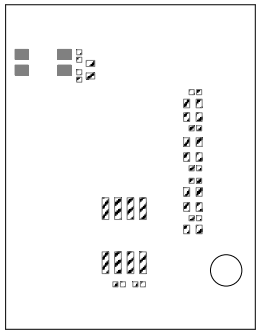
Solder stop mask SOL (.STS)

Rev. B

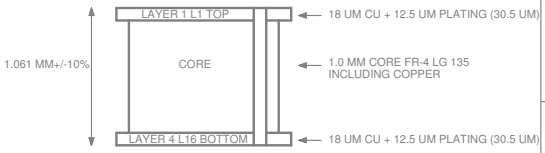
DRILL CHART: TOP TO BOTTOM

Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	61	YES
×	2	36	0.91	14	YES
◳	3	40	1.02	38	YES
◇	4	126	3.20	1	NOT

LAYER-STACK



STACK-UP FOR REFERENCE



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Domino Core

Domino Pi

Domino Qi

Domino JTAG SPI

24/08/14 11:50

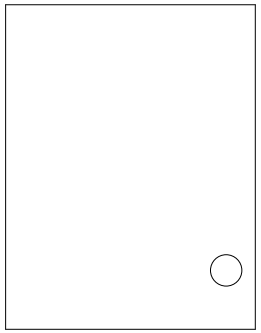
Cream frame CMP (.CRC)

Rev. B

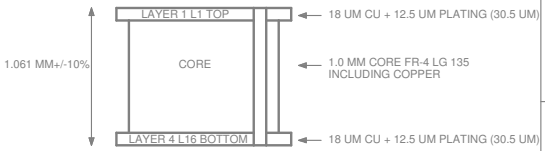
DRILL CHART: TOP TO BOTTOM

LAYER-STACK

Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	61	YES
×	2	36	0.91	14	YES
◳	3	40	1.02	38	YES
◈	4	126	3.20	1	NOT



STACK-UP FOR REFERENCE



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Domino Core

Domino Pi

Domino Qi

Domino JTAG SPI

24/08/14 11:50

Cream frame SOL (.CRS)

Rev. B

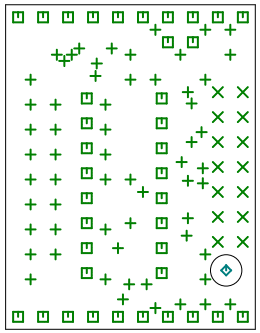
DRILL CHART: TOP TO BOTTOM

LAYER-STACK

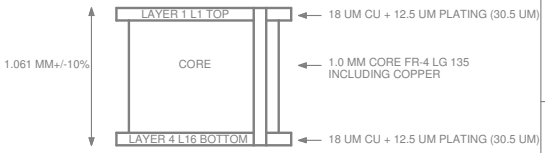
01-16

01-20

Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	61	YES
×	2	36	0.91	14	YES
□	3	40	1.02	38	YES
◇	4	126	3.20	1	NOT



STACK-UP FOR REFERENCE



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Domino Core

Domino Pi

Domino Qi

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Domino JTAG SPI

24/08/14 11:50

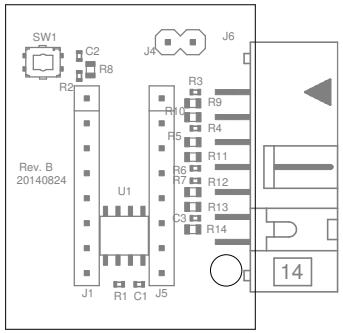
Drill data (.DRD)

Rev. B

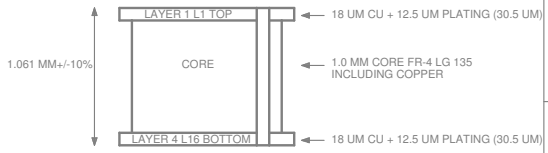
LAYER-STACK

DRILL CHART: TOP TO BOTTOM

Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	61	YES
×	2	36	0.91	14	YES
◳	3	40	1.02	38	YES
◇	4	126	3.20	1	NOT



STACK-UP FOR REFERENCE



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Domino Core

Domino Pi

Domino Qi

Domino JTAG SPI

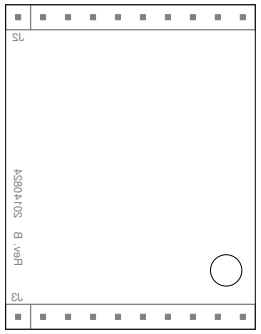
24/08/14 11:50

Component Assembly CMP (.ASC) | Rev. B

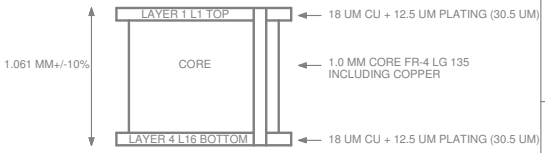
LAYER-STACK

DRILL CHART: TOP TO BOTTOM

Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	61	YES
×	2	36	0.91	14	YES
◳	3	40	1.02	38	YES
◈	4	126	3.20	1	NOT



STACK-UP FOR REFERENCE



NOTES:

1. PRINTED CIRCUIT BOARD MADE FROM NEMA GRADE FR-4 TG 135 EPOXY LAMINATE WITH 18 UM COPPER PLATING AND 1 MM THICKNESS.
2. ALL DIMENSIONS ARE GIVEN IN MILLIMETERS EXCEPT TRACE WIDTH/SPACE.
3. CIRCUIT PATHS ARE FOR REFERENCE ONLY.
4. HOLE SIZES SHOWN ARE FINISHED DIAMETERS AFTER PLATING.
5. BOARD PLATED USING REFLOW OR SIMILAR METHOD.
6. BOARD TO HAVE WHITE SOLDER MASK ON PLATED SURFACES USING WET FILM SR100 OR SR1010 EPOXY.
EQUIVALENT WET OR DRY FILM MAY BE USED.
7. SILKSCREEN BOARD USING BLACK INK. DISTORTION OF SILKSCREEN IS ACCEPTABLE OVER TRACES. EPOXY INK ON PLATED LANDS IS NOT ACCEPTABLE
8. THE FOLLOWING INFORMATION APPLIES TO THIS BOARD:
   * 2 COPPER LAYERS
   * 1 MM BOARD THICKNESS
   * REQUIRES TOP AND BOTTOM SIDE SILKSCREENS

Domino Core

Domino Pi

Domino Qi

Domino JTAG SPI

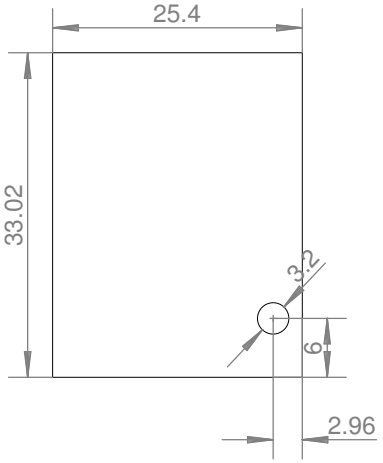
24/08/14 11:50

Component Assembly SOL (.ASS) | Rev. B

DRILL CHART: TOP TO BOTTOM

Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	61	YES
×	2	36	0.91	14	YES
◳	3	40	1.02	38	YES
◇	4	126	3.20	1	NOT

LAYER-STACK



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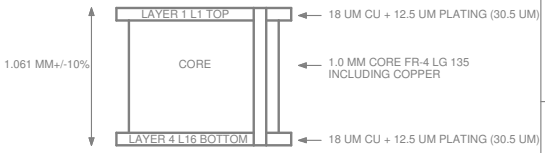

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Domino Core
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Outline (.OLN) | Rev. B

DRILL CHART: TOP TO BOTTOM

Sym	N°	Mils	MM	Qty	Plated
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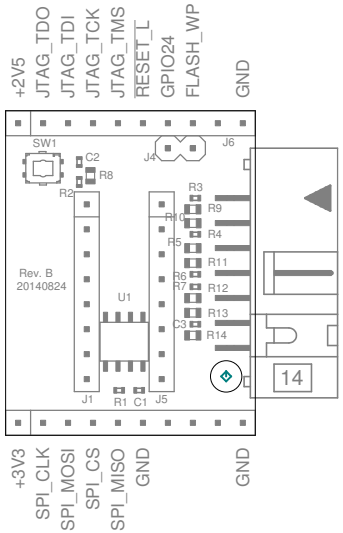
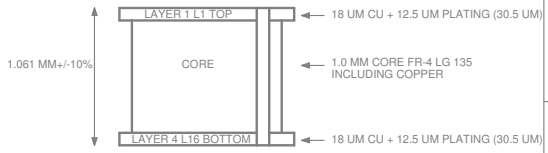
LAYER-STACK

01-20



STACK-UP FOR REFERENCE



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Domino Qi

Domino JTAG SPI

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Pinout (.PIN)

Rev. B

Domino JTAG SPI Rev. B

Item	Qty	Value	Manufacturer	Device	Package	Reference	Description	Remarks
1	2	100n	ANY	C0402_100n_X7R_10%_CER_50V	C0402	C1, C3	CAP CER 0.1UF 50V 10% X7R 0402	
2	1	10n	ANY	C0402_10n_X7R_10%_CER_50V	C0402	C2	CAP CER 10000PF 50V 10% X7R 0402	
3	2	MH8-1	ANY	MH8-1-0.1	MH8-1-0.1	J1, J5	CONN HEADER VERT .100 1ROW 8POS 8.08 HEAD 3.05 TAIL 15AU	
4	2	MH10-1	ANY	MH10-1-0.1	MH10-1-0.1	J2, J3	CONN HEADER VERT .100 1ROW 10POS 8.08 HEAD 3.05 TAIL 15AU	
5	1	MH2-1	ANY	MH2-1-0.1	MH2-1-0.1	J4	CONN HEADER VERT .100 1ROW 2POS 8.08 HEAD 3.05 TAIL 15AU	
6	1	MHRA7-2-0.1	ANY	MHRA7-2-0.1	MHRA7-2-0.1	J6	CONN HEADER SHROUDED R/A .100 2ROWS 7POS 6.10 HEAD 3.05 TAIL 15AU	
7	6	10k	ANY	R0402_10k_5%_62.5mW	R0402	R1, R2, R3, R4, R6, R7	RES 10K OHM 1/16W 5% 0402 SMD	
8	4	0R	ANY	R0603_0R_5%_125mW	R0603	R5(DNP), R8(DNP), R9(DNP), R10, R11, R12, R1	RES 0.0 OHM 1/8W JUMP SMD 0603	
9	1	IT-1124SMD	SZJUSTWELL ELECTRONICS	IT-1124SMD	IT-1124SMD	SW1	SWITCH TACTILE SPST-NO 0.02A 15V	
10	0	SPI_FLASH	ANY	SPI_FLASH	SOIC-8	U1(DNP)	SPI FLASH SMD	